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tion of:

Mak, et al.

Serial No.: 09/885,609

Confirmation No.: 5337

Filed:

June 20, 2001

For:

System And Method To Form A Composite Film Stack Utilizing Sequential **Deposition Techniques** 

Group Art Unit: 2818

Examiner:

Renee R. Berry

Commissioner for Patents Washington, D.C. 20231

Dear Sir:

## CERTIFICATE OF MAILING

37 CFR 1.8

I hereby certify that this correspondence is being deposited on 2003 with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231

Signature

## SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

The Applicants, and the Attorney who signs below on the basis of the information supplied by the inventor and the information in his file, submit herewith patents; publications, or other information of which they are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR § 1.56.

While the information submitted in this Supplemental Information Disclosure Statement may be material pursuant to 37 CFR § 1.56, it is not intended to constitute an admission that any patent, publication, or other information referred to therein is prior art for this invention unless specifically designated as such.

In accordance with 37 CFR § 1.97, this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or hat no other possibly material information as defined under 37 CFR § 1.56(a) exists. NDIM1 00000082 200782 09885609

180.00 CH

The patents and/or publications submitted herewith are set forth on the attached Form PTO-1449.

The Commissioner is hereby authorized to charge sum of \$180.00 is due under 37 CFR § 1.17(p) pursuant to § 1.97, and any other fee necessary to make this submission timely, to the Deposit Account No. 20-0782/APPM/5351/BTP.

Respectfully submitted,

B. Todd Patterson

Registration No. 37,906

MOSER, PATTERSON & SHERIDAN, L.L.P.

3040 Post Oak Blvd., Suite 1500

Houston, TX 77056

Telephone: (713) 623-4844 Facsimile: (713) 623-4846

Attorney for Applicants

						S	heet 1 of 2 s	heet(s
U.S. Department of Commerce, Patent and Trademark Office					Docket No.		Serial No.	
(PTO Form 1449 modified) MAR 0 5 2003					APPM/5351/CPI/L/B/ PJS		09/885,609	
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT  (Use several sheets if necessary)					Applicant		Confirmation No.:	
					Mak, et al.		5337	
					Filing Date		Group	
Examiner Renee R. Berry					June 20, 2002		2818	
U.S. Paten	t Docu	ments					•	
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	A1	6,481,945	11-19-2002	Hasper, et al.	414	217	06-04-1999	
	A2	6,478,872	11-12-2002	Chae, et al.	117	88	12-20-1999	
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	B1	EP 1 167 569 V	01-02-2002	EP	C23C	16/455 2	2	Х
	B2	WO 02/08488 -	01-31-2002	WIPO	C23C	16/44	RES	Х
	B3	WO 01/17692 ~	03-15-2001	WIPÓ	B05C	11/00		X
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*Examiner Initial		Including Author, Title, Date, Pertinent Pages, Etc.						
	C1							
	C2				T			
Examiner					Date Cons	sidered		

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.